

Welcome to E-XFL.COM

Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	20 ns
Voltage Supply - Internal	4.5V ~ 5.5V
Number of Logic Elements/Blocks	-
Number of Macrocells	12
Number of Gates	-
Number of I/O	-
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-LCC (J-Lead)
Supplier Device Package	28-PLCC (11.51x11.51)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/gal26cv12b-20lji

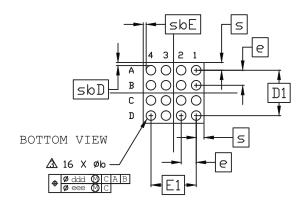
Email: info@E-XFL.COM

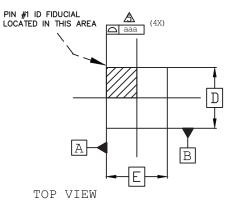
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

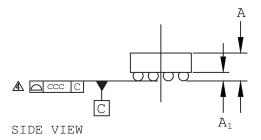


16-Ball WLCS Package Option 2: iCE40 UltraLite[™]

Dimensions in Millimeters







NOTES:

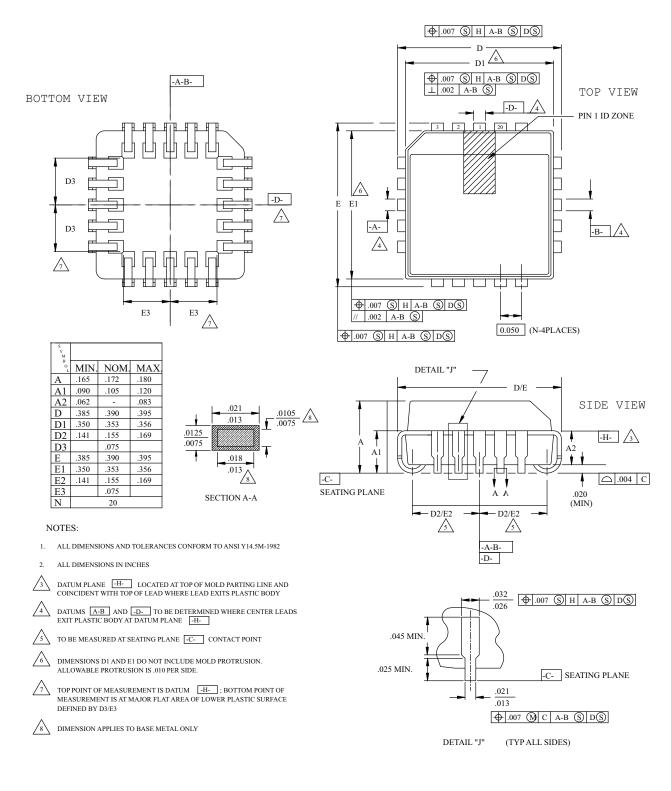
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- ▲ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \bigtriangleup primary datum c and seating plane are defined by the spherical crowns of the solder bumps.
- \bigtriangleup BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

Min.	Nom.	Max.
0.413	0.452	0.491
0.122	0.152	0.182
0.188	0.218	0.248
1.	409 BS	C
1.	409 BS	С
	L.05 BSC)
	1.05 BSC)
().35 BSC	2
-	0.180	-
0.067	0.071	0.072
0.067 0.071 0.072		
0.03		
0.03		
0.050		
0.015		
	0.413 0.122 0.188 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1. 1.	0.413 0.452 0.122 0.152 0.188 0.218 1.409 BS 1.409 BS 1.05 BS 0.35 BS 0.35 BS 0.071 0.067 0.071 0.067 0.03 0.03 0.03



20-Pin PLCC Package

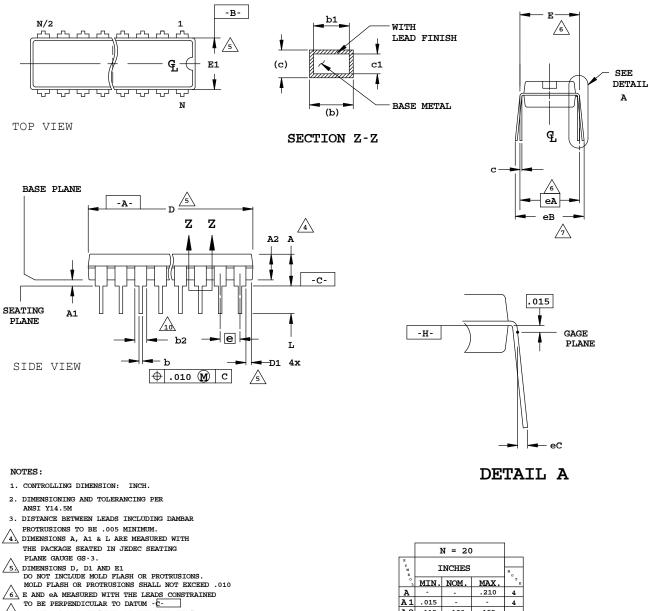
Dimensions in Inches





20-Pin Plastic DIP Package

Dimensions in Inches



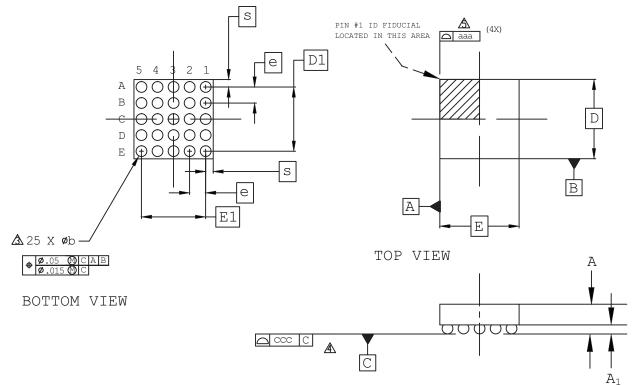
- 10 BE PERPENDICULAR TO DATUM 2 BAND C ARE MEASURED AT THE LEAD TIPS \wedge WITH THE LEADS UNCONSTRAINED.
- 8. N IS THE MAXIMUM NUMBER OF LEAD
- POSITIONS. 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10, b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR
- PROTRUSIONS SHALL NOT EXCEED .010
- 11 DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

- 4 .210 A1 .015 A2 .115 .130 .195 b .014 .018 .022 b1 .014 .020 .018 .070 b2 .045 .060 10 .014 C .008 .010 C1 .008 .010 .011 D .980 1.030 1.060 5 D1 .005 5 .310 .325 E .300 6 E1 .240 .250 .280 5 е .100 BSC eA 300 BSC 6 .430 7 eB eC .000 7 .060 L .115 .130 .150 4



25-Ball WLCS Package (0.35 mm Pitch)

Dimensions in Millimeters



SIDE VIEW

Notes:

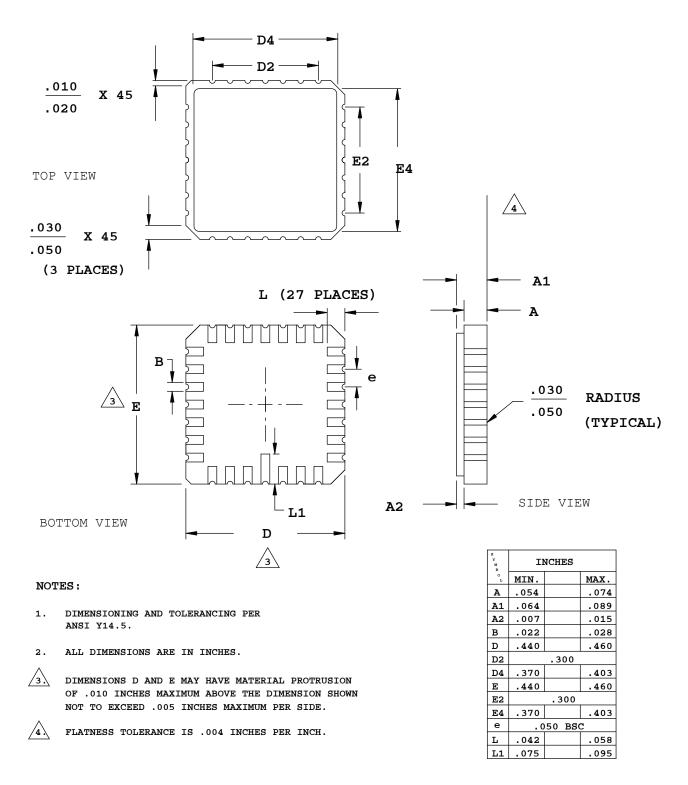
- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- A PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- ▲ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom. Ma	ax.
A	0.413	0.452	0.491
A1	0.122	0.152	0.182
b	0.188	0.218	0.248
D	1.71 BSC		
E	1.71 BSC		
D1		1.40 BS	SC
E1		1.40 BS	SC
e		0.35 BS	SC
aaa	0.03		
ccc	0.03		
S	-	0.015	-



28-Pin LCC Package

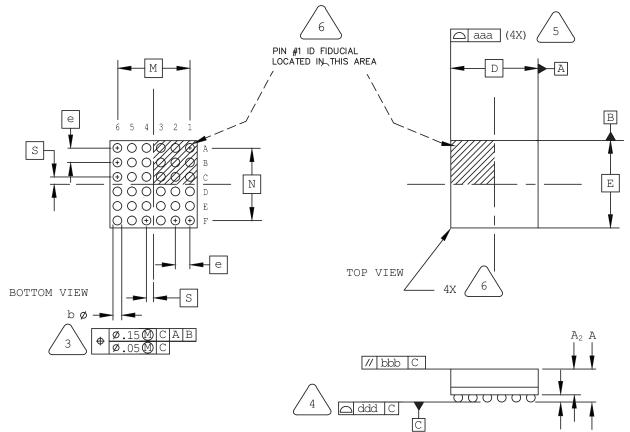
Dimensions in Inches





36-Ball ucfBGA Package: iCE40 Ultra™

Dimensions in Millimeters



SIDE	VIEW

NOTES:	UNLESS OTHERWISE SPECIFIED
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2.	ALL DIMENSIONS ARE IN MILLIMETERS.
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
\cap	

6

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

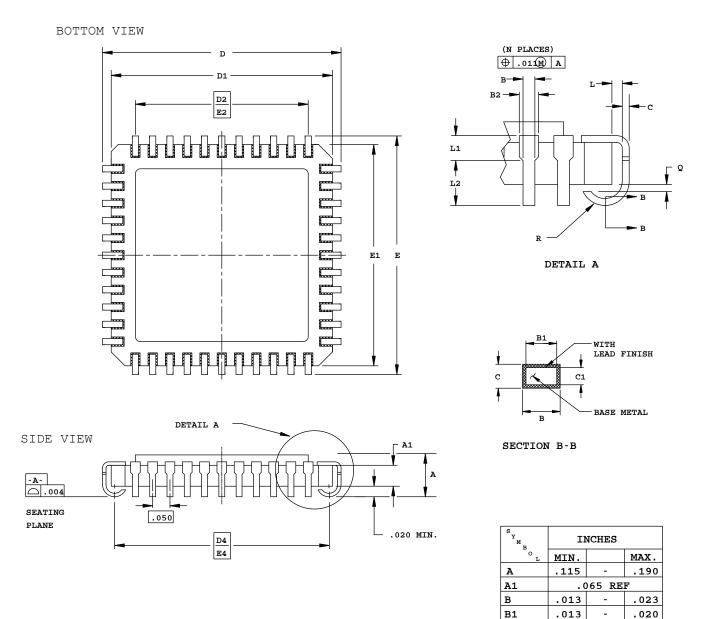
SYMBOL	MIN.	NOM.	MAX.
A	-	0.81	0.91
Al	0.12	-	-
A2	_	_	0.70
D/E	2	.50 BSC	
M/N	2.00 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
е	0.40 BSC		
aaa	-	-	0.10
bbb	-	_	0.10
ddd	_	_	0.10

 A_1



44-Pin JLCC Package

Dimensions in Inches



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

B2

С

C1

D/E

D1/E1

D2/E2

D4/E4

г

L1

L2

Q

R

N

.022

.007

.007

.675

.620

.005

.020

.025

.003

.020

-

.690

.500 BSC

.630 BSC

-

-

-

44

.035

.013

010

.700

.660

-

-

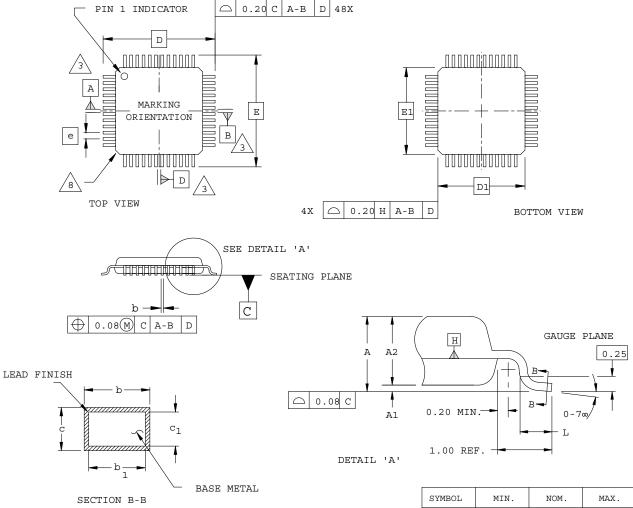
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.040



48-Pin TQFP Package (1.0 mm thick)

Dimensions in Millimeters



NOTES:

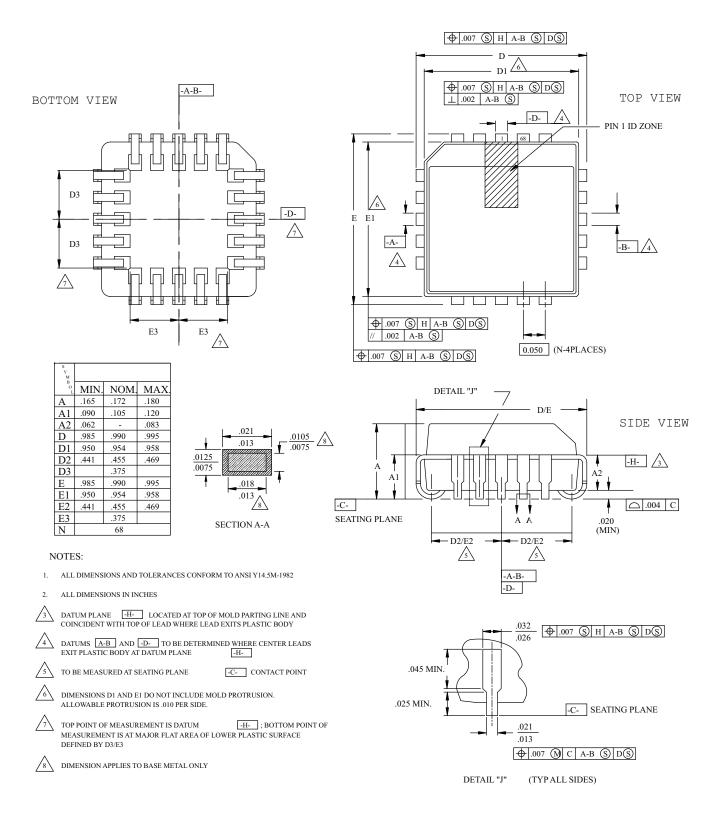
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- $/_3$ datums a, b and d to be determined at datum plane H.
- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.05	-	0.15
A2	.95	1.00	1.05
D		9.00 BSC	
D1		7.00 BSC	
Е	9.00 BSC		
E1	7.00 BSC		
L	0.45 0.60 0.75		
N	48		
е	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
с	0.09	0.15	0.20
c1	0.09	0.13	0.16



68-Pin PLCC Package

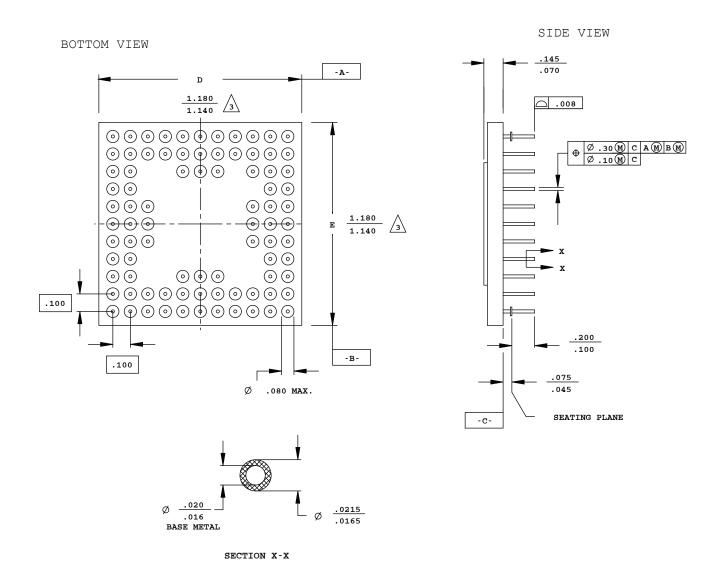
Dimensions in Inches





84-Pin CPGA Package

Dimensions in Inches



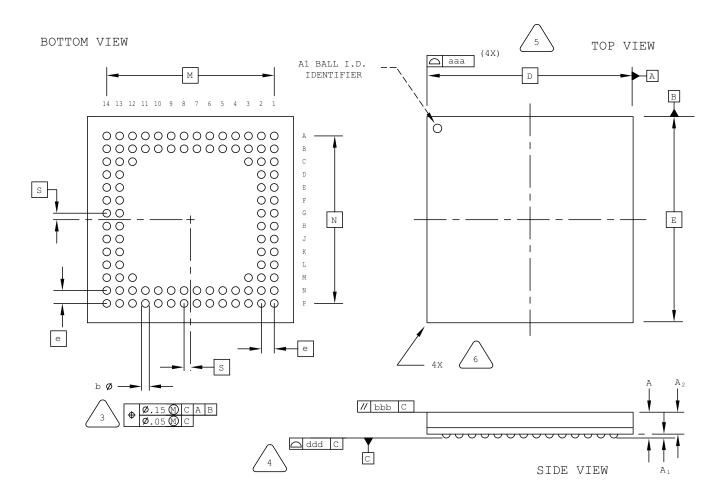
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- <u>J</u>. DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .006 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .003 INCHES MAXIMUM PER SIDE.



100-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES 1. PER ANSI Y14.5M. 2. ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, 3 PARALLEL TO PRIMARY DATUM C PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL 4 CROWNS OF THE SOLDER BALLS. BILATERAL TOLERANCE ZONE IS APPLIED 5 TO EACH SIDE OF THE PACKAGE BODY.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

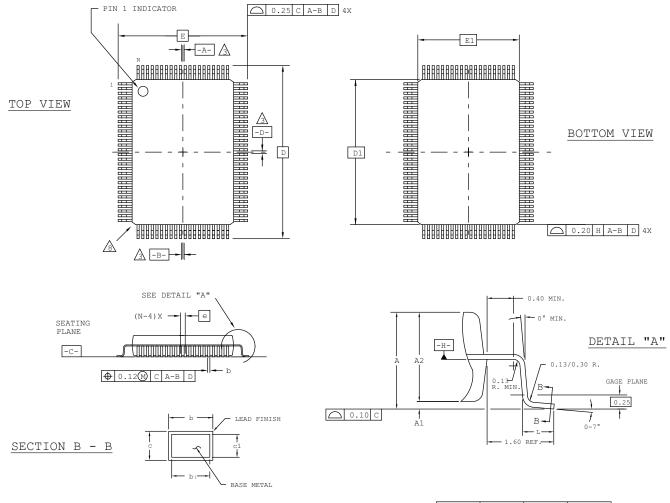
6

SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.23	1.35
A1	0.15	-	_
A2	_	_	1.10
D/E	8	.00 BSC	
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa			0.10
bbb	-	-	0.10
ddd	_	_	0.08



100-Pin PQFP Package

Dimensions in Millimeters



NOTES:

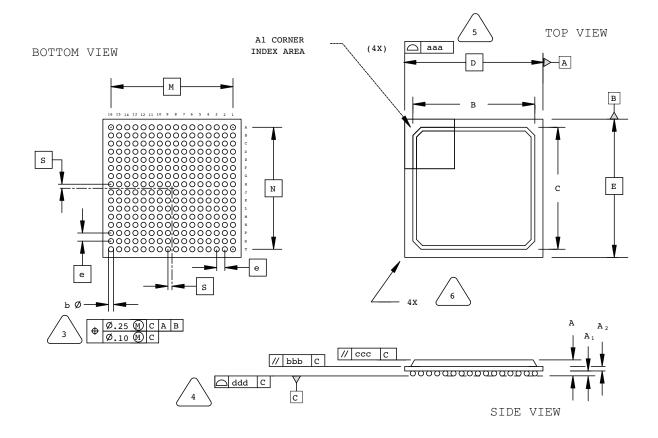
- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- Δ datums a, b and d to be determined at datum plane H.
- 4.0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6.0 SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- A EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL MIN. NOM. MAX. _ _ Α 3 40 0.25 A1 _ 0.50 A2 2.50 2.70 2.90 23.20 BSC D D1 20.00 BSC Е 17.20 BSC 14.00 BSC E1L 0.73 0.88 1.03 Ν 100 0.65 BSC e b 0.22 _ 0.40 b1 0.22 0.30 0.36 0.11 _ 0.23 С c1 0.11 0.15 0.19



256-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\fbox{\cite{C}}$



5

6

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

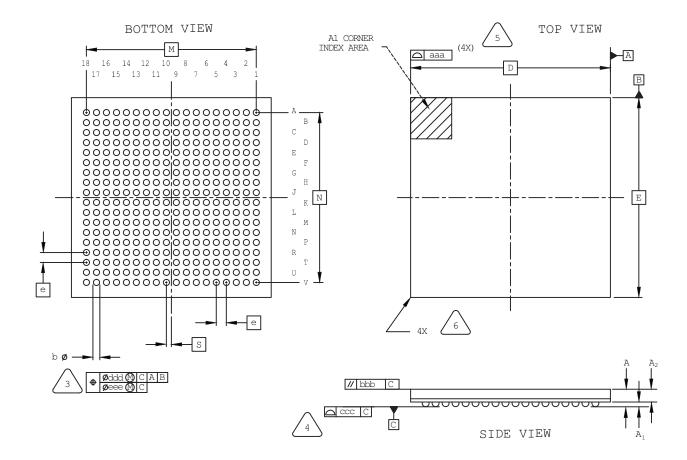
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	1	7.00 BSC	
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	_	0.25
ccc	-	-	0.35
ddd	-	-	0.20



324-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



6

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

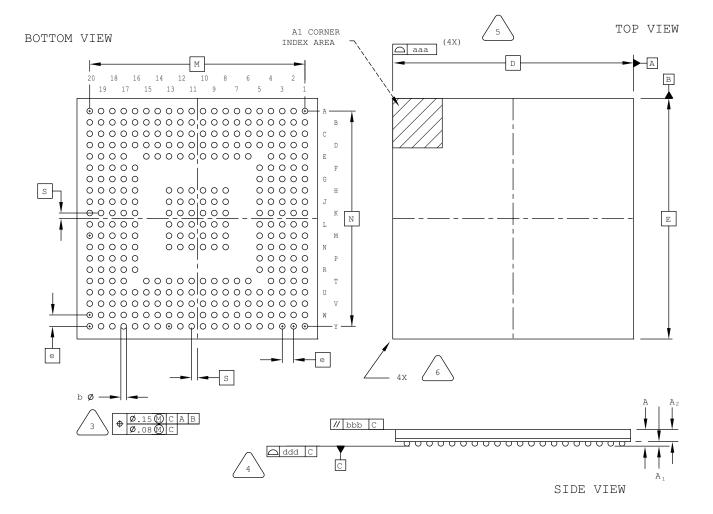
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
Al	0.15	0.24	-
A2	_	0.66	-
D/E	1	0.00 BSC	
M/N		8.50 BSC	
S	0.25 BSC		
b	0.25 0.30 0.35		
е	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		



332-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

З

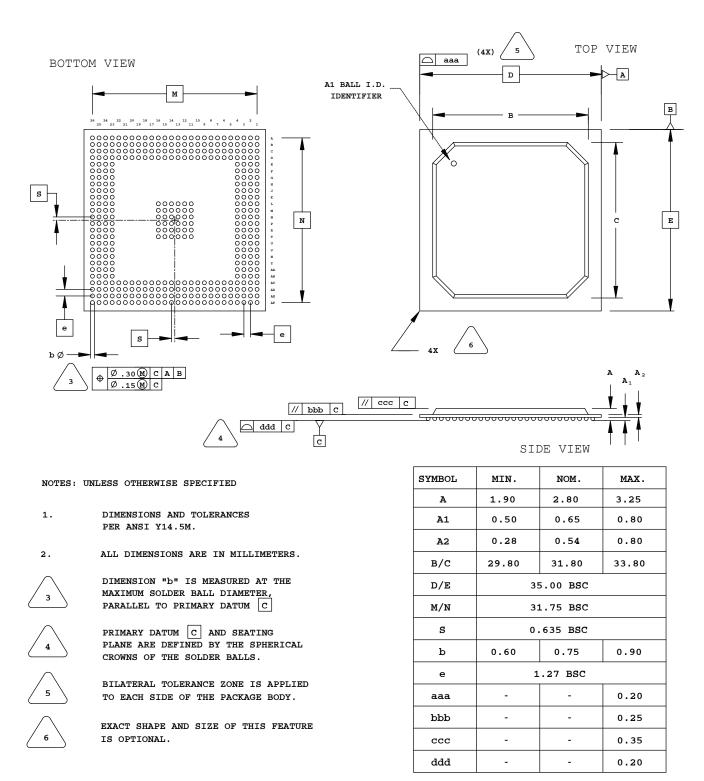
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
 - DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
 - PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
 - EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	_	-	2.00
A1	0.25	-	-
A2	0.65	_	-
D/E	17.0 BSC		
M/N	15.2 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	_	_	0.15
bbb	_	_	0.20
ddd	-	-	0.20



388-Ball BGA Package

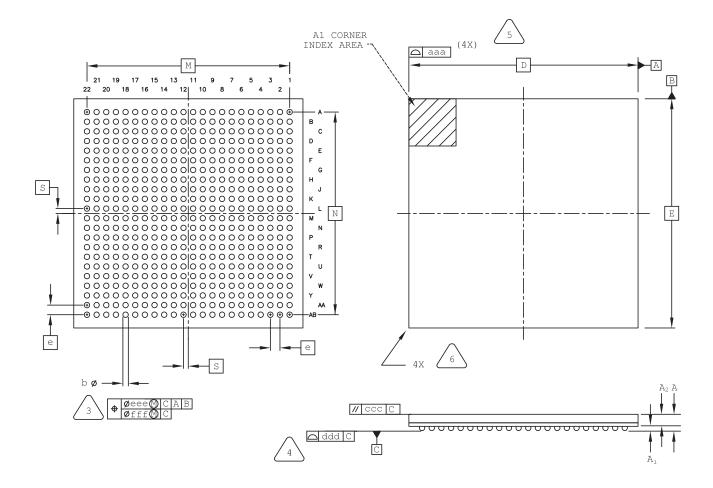
Dimensions in Millimeters





484-Ball caBGA Package (19x19 mm Body)

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

3

4

5

6

7

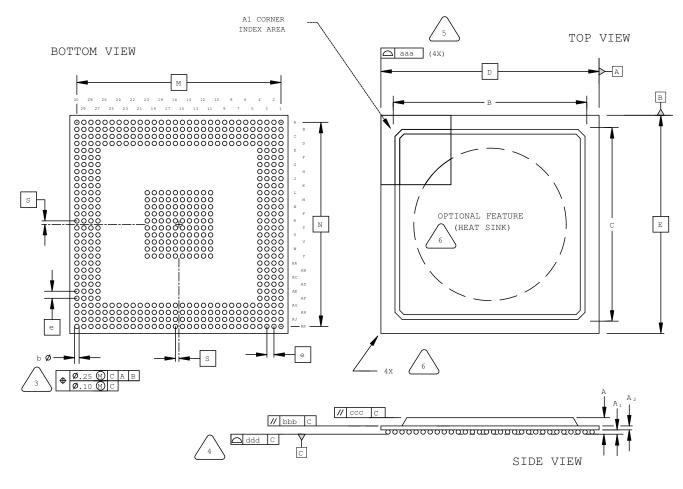
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
 - DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
 - PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
 - EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
 - JEDEC REFERENCE: MO-275A

SYMBOL	MIN.	NOM.	MAX.	
A	-	-	1.70	
A1	0.25	-	-	
A2	0.65	-	-	
D/E	1	9.0 BSC		
M/N	1	6.8 BSC		
S	0	0.40 BSC		
b	0.40	0.45	0.50	
е	C	.80 BSC		
aaa	-	-	0.15	
ccc	_	-	0.20	
ddd	_	-	0.20	
eee	_	-	0.15	
fff	_	-	0.08	



516-Ball fpBGA Package

Dimensions in Millimeters



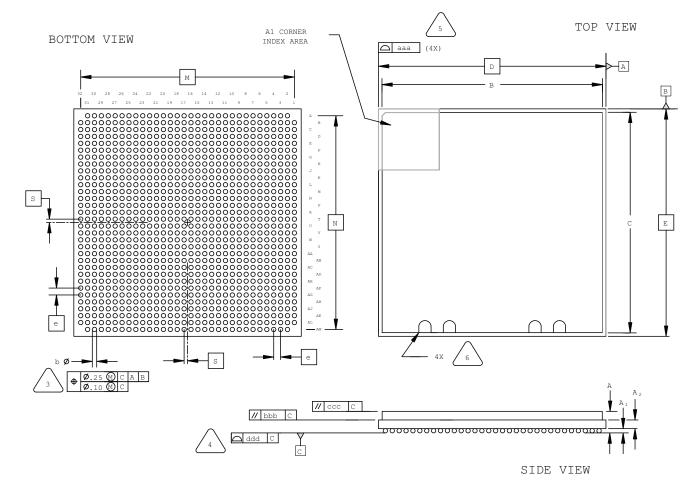
NOTES: UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES 1. PER ANSI Y14.5M. 2. ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY. EXACT SHAPE AND SIZE OF THIS FEATURE 6 IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
Al	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



1020-Ball Organic fcBGA Package

Dimensions in Millimeters



 NOTES: UNLESS OTHERWISE SPECIFIED
 A

 1.
 DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
 A1

 2.
 ALL DIMENSIONS ARE IN MILLIMETERS.
 B/C

 3
 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
 D/E

 4
 PRIMARY DATUM C
 AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 b

 5
 BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
 e

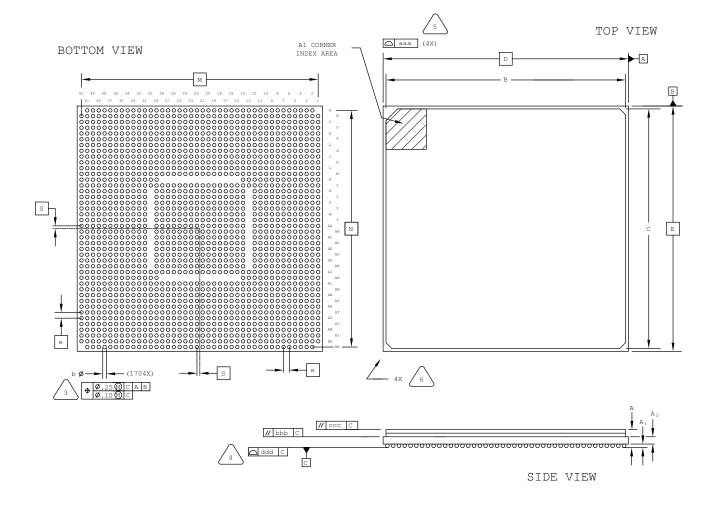
 6
 EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
 ccc

SYMBOL	MIN.	NOM.	MAX.
A	2.52	3.12	3.82
A1	0.30	0.50	0.70
A2	1.24 REF		
B/C	31.10	32.00	32.90
D/E	33.00 BSC		
M/N	31.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	_	0.35
ddd	_	-	0.20



1704-Ball Organic fcBGA Package

Dimensions in Millimeters



NOTES:	UNLESS OTHERWISE SPECIFIED	
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.	
2.	ALL DIMENSIONS ARE IN MILLIMETERS.	
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C	
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.	
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.	
6	EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.	

SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.35	0.50	0.65
A2	1.20 REF		
B/C	41.70	42.00	42.30
D/E	42.50 BSC		
M/N	42.50 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.23